

Cheng Qian

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

34
papers

379
citations

11
h-index

18
g-index

40
ext. papers

523
ext. citations

2.8
avg. IF

3.72
L-index

#	Paper	IF	Citations
34	Degradation Analysis for Reliability of Optoelectronics 2022 , 317-350		
33	Tensile characterization and constitutive modeling of sintered nano-silver particles over a range of strain rates and temperatures. <i>Microelectronics Reliability</i> , 2022 , 132, 114536	1.2	1
32	An Electric Fence-Based Intelligent Scheduling Method for Rebalancing Dockless Bike Sharing Systems. <i>Applied Sciences (Switzerland)</i> , 2022 , 12, 5031	2.6	1
31	Application of MICMAC, Fuzzy AHP, and Fuzzy TOPSIS for Evaluation of the Maintenance Factors Affecting Sustainable Manufacturing. <i>Energies</i> , 2021 , 14, 1436	3.1	22
30	. <i>IEEE Photonics Journal</i> , 2020 , 12, 1-18	1.8	4
29	Experimental Investigation on the Sintering Kinetics of Nanosilver Particles Used in High-Power Electronic Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020 , 10, 1101-1109	1.7	4
28	High Temperature Performance Evaluation and Life Prediction for Titanium Modified Silicone Used in Light-Emitting Diodes Chip Scale Packages. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2020 , 142,	2	4
27	Characterization and reconstruction for stochastically distributed void morphology in nano-silver sintered joints. <i>Materials and Design</i> , 2020 , 196, 109079	8.1	2
26	Application of artificial neural networks for quantitative damage detection in unidirectional composite structures based on Lamb waves. <i>Advances in Mechanical Engineering</i> , 2020 , 12, 168781402091473	1.2	10
25	An Archimedean Copula Function-Based Prediction Method for High-Power White LED Considering Multi-Performance. <i>IEEE Transactions on Electron Devices</i> , 2019 , 66, 3405-3410	2.9	3
24	Investigation of Step-Stress Accelerated Degradation Test Strategy for Ultraviolet Light Emitting Diodes. <i>Materials</i> , 2019 , 12,	3.5	11
23	. <i>IEEE Access</i> , 2019 , 7, 68495-68502	3.5	8
22	Characterization of Stochastically Distributed Voids in Sintered Nano-Silver Joints 2019 ,		1
21	A Heuristic Hybrid Optimization Approach for Spare Parts and Maintenance Workers Under Partial Pooling. <i>IEEE Access</i> , 2019 , 7, 137835-137847	3.5	1
20	Effects of Voids on Mechanical and Thermal Properties of the Die Attach Solder Layer Used in High-Power LED Chip-Scale Packages. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018 , 8, 1254-1262	1.7	16
19	A design and qualification of LED flip Chip-on-Board module with tunable color temperatures. <i>Microelectronics Reliability</i> , 2018 , 84, 140-148	1.2	4
18	Thermal Management on IGBT Power Electronic Devices and Modules. <i>IEEE Access</i> , 2018 , 6, 12868-12884	3.5	96

17	An Alternative Lifetime Model for White Light Emitting Diodes under Thermal/Electrical Stresses. <i>Materials</i> , 2018 , 11,	3.5	11
16	Study of ultraviolet assisted cure mechanism of the phosphor/silicone composites used in White LEDs 2018 ,		1
15	PHM of Light-Emitting Diodes 2018 , 377-430		
14	A Gamma Process-Based Prognostics Method for CCT Shift of High-Power White LEDs. <i>IEEE Transactions on Electron Devices</i> , 2018 , 65, 2909-2916	2.9	10
13	A novel lifetime prediction for integrated LED lamps by electronic-thermal simulation. <i>Reliability Engineering and System Safety</i> , 2017 , 163, 14-21	6.3	27
12	Thermal/luminescence characterization and degradation mechanism analysis on phosphor-converted white LED chip scale packages. <i>Microelectronics Reliability</i> , 2017 , 74, 179-185	1.2	17
11	Studies of the light output properties for a GaN based blue LED using an electro-optical simulation method. <i>Microelectronics Reliability</i> , 2017 , 74, 173-178	1.2	3
10	Prediction of Lumen Depreciation and Color Shift for Phosphor-Converted White Light-Emitting Diodes Based on A Spectral Power Distribution Analysis Method. <i>IEEE Access</i> , 2017 , 5, 24054-24061	3.5	24
9	Phosphor/silicone interaction effects in high power white light emitting diode packages. <i>Journal of Materials Science: Materials in Electronics</i> , 2017 , 28, 17557-17569	2.1	11
8	Numerical Thermal Analysis and Optimization of Multi-Chip LED Module Using Response Surface Methodology and Genetic Algorithm. <i>IEEE Access</i> , 2017 , 5, 16459-16468	3.5	8
7	Color Shift Failure Prediction for Phosphor-Converted White LEDs by Modeling Features of Spectral Power Distribution with a Nonlinear Filter Approach. <i>Materials</i> , 2017 , 10,	3.5	19
6	Photometric and Colorimetric Assessment of LED Chip Scale Packages by Using a Step-Stress Accelerated Degradation Test (SSADT) Method. <i>Materials</i> , 2017 , 10,	3.5	11
5	Colour shift and mechanism investigation on the PMMA diffuser used in LED-based luminaires. <i>Optical Materials</i> , 2016 , 54, 282-287	3.3	23
4	2016 ,		6
3	Analysis of photoluminescence mechanisms and thermal quenching effects for multicolor phosphor films used in high color rendering white LEDs 2016 ,		2
2	. <i>IEEE Transactions on Device and Materials Reliability</i> , 2015 , 15, 576-587	1.6	13
1	Investigation of photoluminescence and thermal effect of phosphor films used in phosphor-converted white LEDs 2015 ,		3